

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Pre Application of
Toshihiro YAMASHITA, et al.
Serial No.: 09/901,038

Filed: July 10, 2001

: Customer Number: 20277
 : Confirmation Number: 6404
 : Group Art Unit: 1763
 : Examiner: M. Crowell

For: PLASMA PROCESSING SYSTEM IN WHICH WAFER IS RETAINED BY ELECTROSTACTIC CHUCK, PLASMA PROCESSING METHOD AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE

Mail Stop Non-Fee Amendment
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith is an Amendment in the above-identified application.

- No additional fee is required.
 Applicant is entitled to small entity status under 37 CFR 1.27
 Also attached:

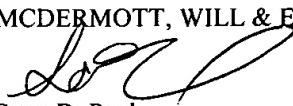
The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	18	20	0	\$18.00 =	\$0.00
Independent Claims	2	3	0	\$86.00 =	\$0.00
Multiple claims newly presented					\$0.00
Fee for extension of time					\$0.00
					\$0.00
Total of Above Calculations					\$0.00

- Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.
- The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

MCDERMOTT, WILL & EMERY


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 TC 1700



Docket No.: 50090-301

PATENT

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re Application of
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Application No.: 09/901,038

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AMENDMENT

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following Amendment and Remarks are submitted in response to the non-final
Office Action dated October 17, 2003.